

Searched on 8-29-2002

IS&R	L1	0	("optic\$2 adj fiber").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
		2002/08/29 08:47			
BRS	L2	119597	optic\$2 adj fiber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
		2002/08/29 08:47			
BRS	L3	554	optic\$2 adj chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
		2002/08/29 08:50			
BRS	L4	12963	optic\$2 with chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
		2002/08/29 08:51			
BRS	L5	3102	adhesiv\$ near4 cavity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
		2002/08/29 08:52			
BRS	L6	3089	2 and 4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/29 08:52
BRS	L7	9	5 and 6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/29 08:52
BRS	L8	2	3 and 7	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/29 08:52

US 20020071641 A1	US-PGPUB	20020613 16	LD/PD module
US 20020015567 A1	US-PGPUB	20020207 5	Sleeve for pig-tailing optical fiber
US 6368890 B1	USPAT 20020409		Top contact VCSEL with monitor
US 5813148 A	USPAT 19980929		Footwear with optical fiber illuminating display areas and control module
US 5737458 A	USPAT 19980407		Optical light pipe and microwave waveguide interconnects in multichip modules formed using adaptive lithography
US 5578156 A	USPAT 19961126		Method of mounting a lens on a light emitting diode
US 5562838 A	USPAT 19961008		Optical light pipe and microwave waveguide interconnects in multichip modules formed using adaptive lithography
US 5525190 A	USPAT 19960611		Optical light pipe and microwave waveguide interconnects in multichip modules formed using adaptive lithography
US 20020015567 A	DERWENT	20020213 5	Optic fiber multi-integrated chip pig-tailing apparatus for optical communication, has symmetrical cavity of sleeve in which bonding fiber and chip are bonded using adhesive